CD74FCT623T

Fast CMOS Octal Bus Transceiver (Three-State)

Features

- **Advanced 0.8 micron CMOS Technology**

- **CD74FCT623T is Pin Compatible with Bipolar FAST™ Series at a Higher Speed and Lower Power Consumption**

- **TTL Input and Output Levels**

- **Extremely Low Static Power**

- **Hysteresis on All Inputs**

Description

The CD74FCT623T is an 8-bit wide non-inverting octal transceiver designed with three-state bus-driving outputs in both the send and receive directions. Designed for asynchronous two-way operation between data buses, the control function allows for maximum flexibility in timing.
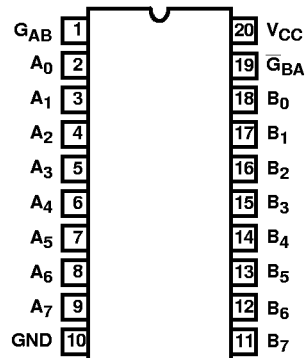
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74FCT623TM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT623ATM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT623CTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT623DTM	-40 to 85	20 Ld SOIC	M20.3-P
CD74FCT623TQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT623ATQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT623CTQM	-40 to 85	20 Ld QSOP	M20.15-P
CD74FCT623DTQM	-40 to 85	20 Ld QSOP	M20.15-P

NOTE: QSOP is commonly known as SSOP.

When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
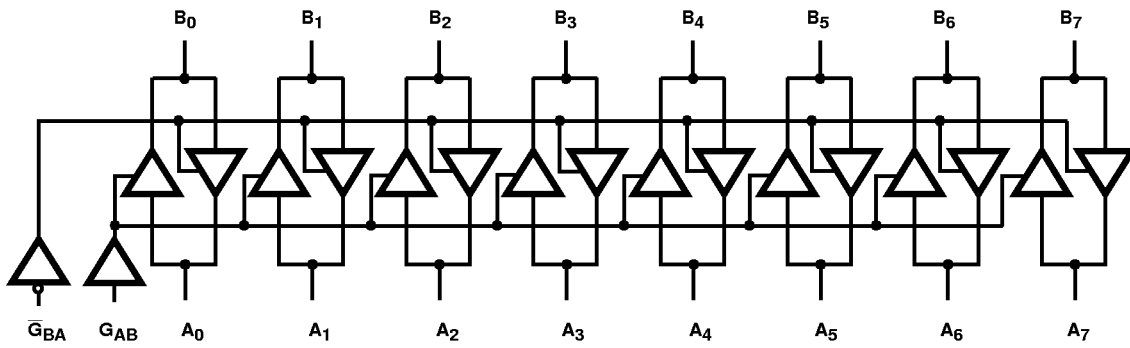
Pinout

CD74FCT623T
(QSOP, SOIC)
TOP VIEW

Pin		Pin	
G_{AB}	1	20	V_{CC}
A_0	2	19	$\overline{G}_{BA}$
A_1	3	18	B_0
A_2	4	17	B_1
A_3	5	16	B_2
A_4	6	15	B_3
A_5	7	14	B_4
A_6	8	13	B_5
A_7	9	12	B_6
GND	10	11	B_7

File Number **4174.2**

Functional Block Diagram

TRUTH TABLE (NOTE 1)

INPUTS		OUTPUTS
$\overline{G}_{BA}$	G_{AB}	
L	L	B Data to A Bus
H	H	A Data to B Bus
H	L	Z
L	H	B Data to A Bus A Data to B Bus

NOTE:

1. H = High Voltage Level
   L = Low Voltage Level
   Z = High Impedance (OFF) State

Pin Descriptions

PIN NAME	DESCRIPTION
$\overline{G}_{BA}$, G_{AB}	Enable Outputs
A_0-A_7	A Bus Inputs or Three-State Outputs
B_0-B_7	B Bus Inputs or Three-State Outputs
GND	Ground
V_{CC}	Power

CD74FCT623T

Absolute Maximum Ratings

DC Input Voltage . . . . -0.5V to 7.0V
DC Output Current 120mA

Operating Conditions

Operating Temperature Range . . . . -40°C to 85°C
Supply Voltage to Ground Potential
   Inputs and V_{CC} Only . . . . -0.5V to 7.0V
Supply Voltage to Ground Potential
   Outputs and D/O Only . . . . -0.5V to 7.0V

Thermal Information

Thermal Resistance (Typical, Note 2)	θ_{JA} (°C/W)
SOIC Package	87
QSOP Package	110

Maximum Junction Temperature . . . . 150°C
Maximum Storage Temperature Range . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . 300°C
   (Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications

PARAMETERS	SYMBOL	(NOTE 3) TEST CONDITIONS		MIN	(NOTE 4) TYP	MAX	UNITS
DC ELECTRICAL SPECIFICATIONS Over the Operating Range, T_A = -40°C to 85°C, V_{CC} = 5.0V ±5%							
Output HIGH Voltage	V_{OH}	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	I_{OH} = -15.0mA	2.4	3.0	-	V
Output LOW Voltage	V_{OL}	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	I_{OL} = 64mA	-	0.3	0.50	V
Input HIGH Voltage	V_{IH}	Guaranteed Logic HIGH Level		2.0	-	-	V
Input LOW Voltage	V_{IL}	Guaranteed Logic LOW Level		-	-	0.8	V
Input HIGH Current	I_{IH}	V_{CC} = Max	V_{IN} = V_{CC}	-	-	1	µA
Input LOW Current	I_{IL}	V_{CC} = Max	V_{IN} = GND	-	-	-1	µA
High Impedance Output Current	I_{OZH}	V_{CC} = Max	V_{OUT} = 2.7V	-	-	1	µA
	I_{OZL}		V_{OUT} = 0.5V	-	-	-1	µA
Clamp Diode Voltage	V_{IK}	V_{CC} = Min, I_{IN} = -18mA		-	-0.7	-1.2	V
Short Circuit Current	I_{OS}	V_{CC} = Max(Note 5), V_{OUT} = GND		-60	-120	-	mA
Power Down Disable	I_{OFF}	V_{CC} = GND, V_{OUT} = 4.5V		-	-	100	µA
Input Hysteresis	V_H			-	200	-	mV
CAPACITANCE T_A = 25°C, f = 1MHz							
Input Capacitance (Note 6)	C_{IN}	V_{IN} = 0V		-	6	10	pF
Output Capacitance (Note 6)	C_{OUT}	V_{OUT} = 0V		-	8	12	pF
POWER SUPPLY SPECIFICATIONS							
Quiescent Power Supply Current	I_{CC}	V_{CC} = Max	V_{IN} = GND or V_{CC}	-	0.1	10	µA
Supply Current per Input at TTL HIGH	ΔI_{CC}	V_{CC} = Max	V_{IN} = 3.4V (Note 7)	-	0.5	2.5	mA
Supply Current per Input per MHz (Note 8)	I_{CCD}	V_{CC} = Max, Outputs Open $\overline{G}_{BA}$ = G_{AB} = GND One Input Toggling 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	-	0.15	0.25	mA/ MHz

CD74FCT623T

Electrical Specifications (Continued)

PARAMETERS	SYMBOL	(NOTE 3) TEST CONDITIONS		MIN	(NOTE 4) TYP	MAX	UNITS
Total Power Supply Current (Note 10)	I_C	V_{CC} = Max, Outputs Open f_{cp} = 10MHz, 50% Duty Cycle $\overline{G}_{BA}$ = G_{AB} = GND, 50% Duty Cycle One Bit toggling at f_I = 5MHz	V_{IN} = V_{CC} V_{IN} = GND	-	1.7	4.0 (Note 9)	mA
			V_{IN} = 3.4V V_{IN} = GND	-	2.0	5.0 (Note 9)	mA
		V_{CC} = Max, Outputs Open f_{cp} = 10MHz, 50% Duty Cycle $\overline{G}_{BA}$ = G_{AB} = GND, 50% Duty Cycle, Eight Bits toggling at f_I = 2.5MHz, 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	-	3.2	6.5 (Note 9)	mA
			V_{IN} = 3.4V V_{IN} = GND	-	5.2	14.5 (Note 9)	mA

Switching Specifications Over Operating Range

PARAMETER	SYMBOL	(NOTE 11) TEST CONDITIONS	T		AT		CT		DT		UNITS
			(NOTE 12) MIN	MAX	(NOTE 12) MIN	MAX	(NOTE 12) MIN	MAX	(NOTE 12) MIN	MAX	
CD74FCT138T											
Propagation Delay A_N to B_N	t_{PLH}, t_{PHL}	C_L = 50pF R_L = 500Ω	1.5	7.5	1.5	5.5	1.5	4.8	1.5	3.8	ns
Propagation Delay B_N to A_N	t_{PLH}, t_{PHL}		1.5	7.5	1.5	5.5	1.5	4.8	1.5	3.8	ns
Output Enable Time $\overline{G}_{BA}$ to A_N	t_{PZH}, t_{PZL}		1.5	9.0	1.5	7.0	1.5	6.1	1.5	5.0	ns
Output Disable Time $\overline{G}_{BA}$ to A_N (Note 13)	t_{PHZ}, t_{PLZ}		1.5	8.0	1.5	6.5	1.5	5.6	1.5	4.3	ns
Output Enable Time G_{AB} to B_N	t_{PZH}, t_{PZL}		1.5	9.0	1.5	7.0	1.5	6.1	1.5	5.0	ns
Output Disable Time G_{AB} to B_N (Note 13)	t_{PHZ}, t_{PLZ}		1.5	8.0	1.5	6.5	1.5	5.6	1.5	4.3	ns

NOTES:

3. For conditions shown as Max or Min, use appropriate value specified under Electrical Characteristics for the applicable device type.

4. Typical values are at V_{CC} = 5.0V, 25°C ambient and maximum loading.

5. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

6. This parameter is determined by device characterization but is not production tested.

7. Per TTL driven input (V_{IN} = 3.4V); all other inputs at V_{CC} or GND.

8. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

9. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP}/2 + f_I N_I)$
    I_{CC} = Quiescent Current
    ΔI_{CC} = Power Supply Current for a TTL High Input (Vin = 3.4V)
    D_H = Duty Cycle for TTL Inputs High
    N_T = Number of TTL Inputs at D_H
    I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
    f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)
    f_I = Input Frequency
    N_I = Number of Inputs at f_I
    All currents are in milliamps and all frequencies are in megahertz.

11. See test circuit and wave forms.

12. Minimum limits are guaranteed but not tested on Propagation Delays.

13. This parameter is guaranteed but not production tested.

Test Circuits and Waveforms

NOTE:

14. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; $Z_{OUT} \leq 50\Omega$; $t_f, t_r \leq 2.5$ns.

FIGURE 1. TEST CIRCUIT

SWITCH POSITION

TEST	SWITCH
t_{PLZ}, t_{PZL}	Closed
$t_{PHZ}, t_{PZH}, t_{PLH}, t_{PHL}$	Open

DEFINITIONS:

C_L = Load capacitance, includes jig and probe capacitance.
R_T = Termination resistance, should be equal to Z_{OUT} of the Pulse Generator.
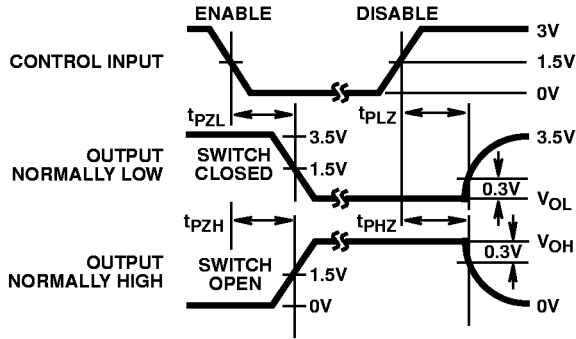

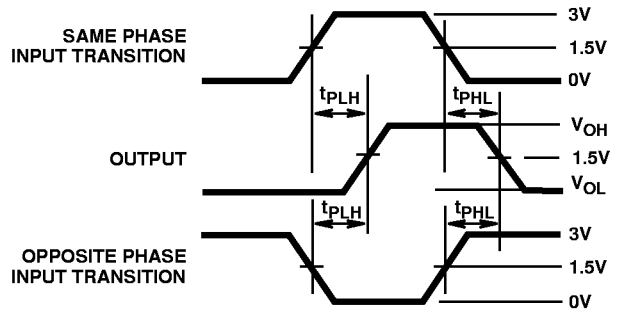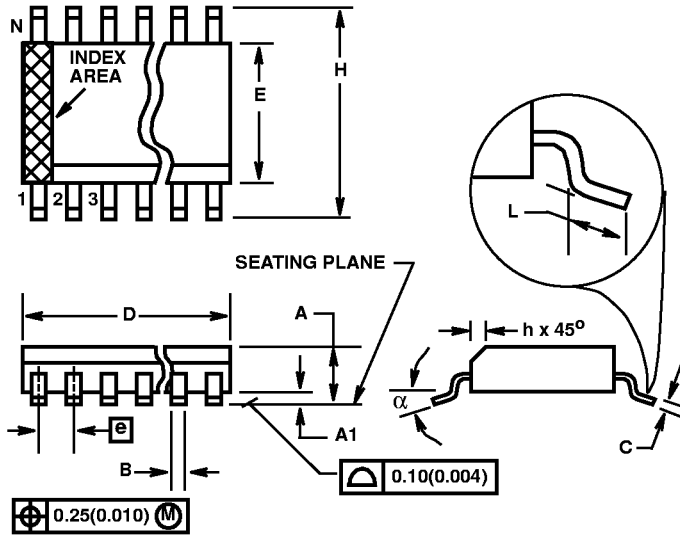
FIGURE 2. ENABLE AND DISABLE TIMING

FIGURE 3. PROPAGATION DELAY

Small Outline Plastic Packages (SOIC)

M20.3-P
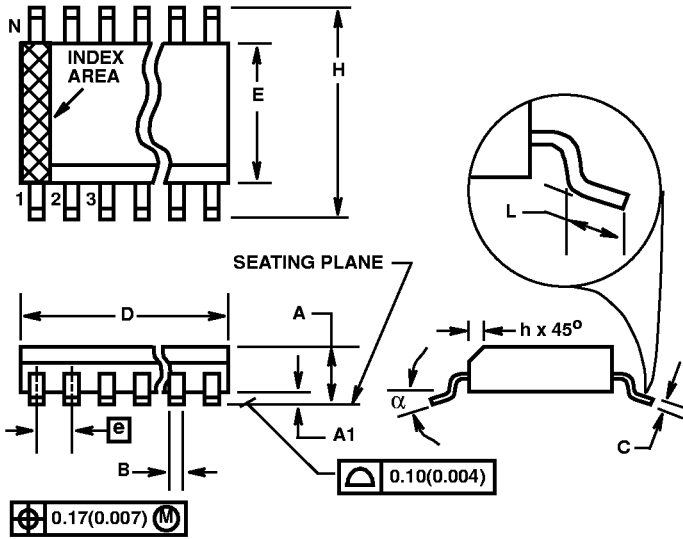**20 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.092	0.105	2.34	2.67	-
A1	0.004	0.012	0.102	0.302	-
B	0.013	0.020	0.330	0.508	-
C	0.009	0.011	0.229	0.279	-
D	0.496	0.512	12.60	13.00	1
E	0.291	0.299	7.39	7.59	2
e	0.050 BSC		1.27 BSC		-
H	0.401	0.411	10.18	10.44	-
h	0.010	0.029	0.254	0.737	-
L	0.016	0.050	0.41	1.27	3
N	20		20		4
α	0°	8°	0°	8°	-

Rev. 0 5/96

NOTES:

1. Dimension "D" does not include mold flash, protrusions or gate burrs.
2. Dimension "E" does not include interlead flash or protrusions.
3. "L" is the length of terminal for soldering to a substrate.
4. "N" is the number of terminal positions.
5. Terminal numbers are shown for reference only.
6. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.

Shrink Small Outline Plastic Packages (SSOP/QSOP)

M20.15-P
20 LEAD SHRINK NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	-
A1	0.007	0.011	0.178	0.279	-
B	0.008	0.012	0.203	0.305	-
C	0.007	0.010	0.178	0.254	-
D	0.337	0.344	8.56	8.74	1
E	0.149	0.157	3.78	3.99	2
e	0.025 BSC		0.635 BSC		-
H	0.228	0.244	5.79	6.20	-
h	0.015		0.38		-
L	0.016	0.050	0.41	1.27	3
N	20		20		4
α	0°	8°	0°	8°	-

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NOTES:

1. Dimension "D" does not include mold flash, protrusions or gate burrs.

2. Dimension "E" does not include interlead flash or protrusions.

3. "L" is the length of terminal for soldering to a substrate.

4. "N" is the number of terminal positions.

5. Terminal numbers are shown for reference only.

6. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.